# austriamicrosystems

## AS1741, AS1742, AS1743 High-Speed, Low-Voltage, Single-Supply, 0.8Ω, Dual SPST Analog Switches

## **1** General Description

The AS1741/AS1742/AS1743 are high-speed, low-voltage, dual single-pole/single-throw (SPST) analog switches.

Fast switching speeds, low ON-resistance, and low power-consumption make these devices ideal for single-cell battery powered applications.

These highly-reliable devices operate from a single +1.6 to +3.6V supply, and are differentiated by the type and number of switches as listed in Table 1.

#### Table 1. Standard Products

Model	Switch Types
AS1741	Two Normally Open (NO) Switches
AS1742	Two Normally Closed (NC) Switches
AS1743	One NO Switch and One NC Switch

The AS1743 supports break-before-make switching.

With very low ON-resistance (RON), RON matching, and RON flatness, the devices can accurately switch signals for sample and hold circuits, digital filters, and op-amp gain switching networks.

The AS1741/AS1742/AS1743 digital logic input is 1.8V CMOS-compatible when using a single +3V supply, and all devices can handle Rail-to-Rail signals.

The devices are available in an 8-pin MSOP package and an 8-pin SOT23 package.

### 2 Key Features

- ON-Resistance:
  - 0.8Ω (+3V supply)
  - 2.5Ω (+1.8V supply)
- Ron Matching: 0.08Ω (+3V supply)
- Ron Flatness: 0.18Ω (+3V supply)
- Supply Voltage Range: +1.6 to +3.6V
- Switching Action: ton = 22ns, toFF = 14ns
- Current-Handling: 250mA Continuous
- Break-Before-Make Switching (AS1743)
- Rail-to-Rail Signal Handling
- 1.8V CMOS Logic Compatible (+3V supply)
- Total Harmonic Distortion: 0.03%
- Operating Temperature Range: -40 to +85°C
- Package Types:
- 8-pin MSOP
- 8-pin SOT23

## **3** Applications

The devices are ideal for use in power routing systems, cordless and mobile phones, MP3 players, CD and DVD players, PDAs, handheld computers, digital cameras, hard drives, and any other application where high-speed signal switching is required.

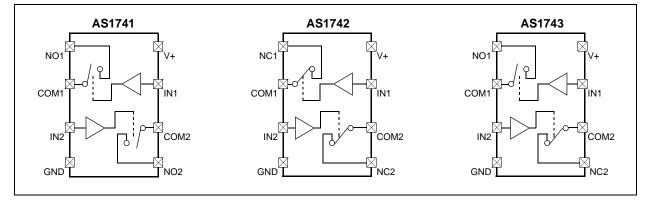


Figure 1. MSOP Block Diagrams

DataSheet

## **4 Absolute Maximum Ratings**

Stresses beyond those listed in Table 2 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Section 5 Electrical Characteristics on page 3 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Parameter	Min	Max	Units	Comments
V+, INx to GND	-0.3	+5	V	
COM <i>x</i> , NO <i>x</i> , NC <i>x</i> to GND <sup>†</sup>	-0.3	V+ + 0.3	V	
COMx, NOx, NCx Continuous Current	-250	+250	mA	
COMx, NOx, NCx Peak Current	-350	+350	mA	Pulsed at 1ms 10% duty cycle
Continuous Power Dissipation (TAMB = +70°C)		362	mW	Derate at 4.5mW/ºC above +70ºC
Electro-Static Discharge		2500	V	HBM Mil-Std883E 3015.7 methods
Latch Up Immunity IN1, IN2		150	mA	Norm: JEDEC 17
Latch Up Immunity all other Pins		250	mA	Nom. JEDEC 17
Operating Temperature Range	-40	+85	°C	
Junction Temperature		+150	°C	
Storage Temperature Range	-65	+150	°C	
Package Body Temperature		+260	Ŷ	The reflow peak soldering temperature (body temperature) specified is in accordance with IPC/JEDEC J-STD-020C "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices"

Table 2.	Absolute	Maximum	Ratings
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<sup>†</sup> Signals on pins COM1, COM2, NO1, NO2, NC1, or NC2 that exceed V+ or GND are clamped by internal diodes. Limit forward-diode current to the maximum current rating.

## **5** Electrical Characteristics

Table 3.	Power Supply Characteristics
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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V+	Power Supply Range		1.6		3.6	V
+	Positive Supply Current	V+ = 3.6V, $V_{INx}$ = 0 or V+, all channels on or off		0.01	1	μA

 $V_{+} = +2.7$  to +3.6V,  $V_{IH} = +1.4V$ ,  $V_{IL} = +0.5V$ ,  $T_{AMB} = T_{MIN}$  to  $T_{MAX}$  (unless otherwise specified). Typ values @  $V_{+} = +3.0V$ ,  $T_{AMB} = +25^{\circ}C$ .

Table 4.	+3V Supply Electrical Characteristics
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Symbol	Parameter	Conditio	ns	Min	Тур	Max	Unit
Analog Swi	tch						
Vcomx, Vnox, Vncx	Analog Signal Range			0		V+	V
Ron	ON-Resistance	V+ = 2.7V, ICOM <i>x</i> = 100mA,	Тамв = +25°С		0.35	0.8	Ω
RON	ON-Resistance	VNOx or $VNCx = 1.5V$	TAMB = TMIN to TMAX			0.9	22
ΔRon	ON-Resistance Match	V+ = 2.7V, ICOM <i>x</i> = 100mA,	Тамв = +25°С		0.02	0.08	Ω
	Between Channels <sup>1</sup>	VNOx or $VNCx = 1.5V$	TAMB = TMIN to TMAX			0.09	52
RFLAT(ON)	ON-Resistance	V+ = 2.7V, ICOM <i>x</i> = 100mA,	Тамв = +25°С		0.02	0.18	Ω
INFLAT(ON)	Flatness <sup>2</sup>	VNOx or $VNCx = 1, 1.5, or 2V$	TAMB = TMIN to TMAX			0.20	52
INO <i>x</i> (OFF),	NOx or NCx Off-	V+ = 3.3V,	Тамв = +25°С	-1		1	
INC <i>x</i> (OFF)	Leakage Current	VCOM <i>x</i> = 0.3 or 3.0V, VNO <i>x</i> or VNC <i>x</i> = 3.0 or 0.3V	TAMB = TMIN to TMAX	-5		5	nA
	COMx Off-Leakage	V + = 3.3V,	Тамв = +25°С	-1		1	
ICOM <i>x</i> (OFF)	Current	VCOM <i>x</i> = 0.3 or 3.0V, VNO <i>x</i> or VNC <i>x</i> = 3.0, 0.3V	TAMB = TMIN to TMAX	-5		5	nA
	COM <i>x</i> On-Leakage	V+ = 3.3V,	Тамв = +25°С	-2		2	
ICOM <i>x</i> (ON)	Current	VCOM <i>x</i> = 3.0 or 0.3V, NO <i>x</i> or VNC <i>x</i> = 3.0 or 0.3V	TAMB = TMIN to TMAX	-10		10	nA
Switch Dyn	amic Characteristics						
	3	VNOx or VNCx = $1.5V$ ,	Тамв = +25°С		13	22	
ton	Turn On Time <sup>3</sup>	RLOAD = $50\Omega$ , CLOAD = $35pF$ , Figures 12, 13	TAMB = TMIN to TMAX			24	ns
torr	3	VNOx or VNCx = $1.5V$ ,	Тамв = +25°С		7	14	
tOFF	Turn Off Time <sup>3</sup>	RLOAD = $50\Omega$ , CLOAD = $35pF$ , Figures 12, 13	TAMB = TMIN tO TMAX			15	ns
topu		$V_{NOx}$ or $V_{NCx} = 1.5V$ ,	Тамв = +25°С		6		
tBBM	Break Before Make <sup>3</sup>	RLOAD = $50\Omega$ , CLOAD = $35p$ , Figure 14 (AS1743)	TAMB = TMIN to TMAX	1			ns
Q	Charge Injection	$V_{GEN} = 3.3V, R_{GEN} = 0,$	8-pin MSOP		6		Эq
4	onarge injection	CLOAD = 1.0nF, Figure 15	8-pin SOT23		5		po
COFF	NO <i>x</i> , NC <i>x</i> Off- Capacitance	f = 1MHz, Fig	ure 16		35		pF
CCOM <i>x</i> (OFF)	COMx Off-Capacitance	f = 1MHz, Fig	ure 16		35		pF
CCOM <i>x</i> (ON)	COMx On-Capacitance	f = 1MHz, Figure 16			35		pF
BW	-3dB On-Channel Bandwidth	Signal = 0, RIN = ROUT = $50\Omega$ , CLOAD = 5pF, Figure 17			130		MHz
Viso	Off-Isolation 4	f = 1MHz, VCOM $x = 1VRMS$ , RLOAD = 50 $\Omega$ , CLOAD = 5pF, Figure 17			-55		dB
	Crosstalk <sup>5</sup>	f = 1MHz, VCOM $x = 1$ VRMS, RLOAD = 50 $\Omega$ , CLOAD = 5pF, Figure 17			-100		dB
THD	Total Harmonic Distortion	f = 20Hz to 20kHz, VCOMx = 2Vp-p, RLOAD = $32\Omega$			0.03		%

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Logic Input						
Vін	Input Logic High		1.4			V
VIL	Input Logic Low				0.5	V
lin	Input Leakage Current	$VIN_X = 0 \text{ or } V+$	-1000	0.1	1000	nA

V + = +1.8V, VIH = +1.0V, VIL = 0.4V, TAMB = TMIN to TMAX (unless otherwise specified). Typ values @ TAMB = +25°C.

Table 5.	+1.8V Supply Electrical Characteristics
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Symbol	Parameter	Conditions			Тур	Max	Unit	
Analog Swit	ch							
Vcom <i>x</i> , Vno <i>x</i> , Vnc <i>x</i>	Analog Signal Range			0		V+	V	
Ron	ON-Resistance	$ICOM_X = 10mA$ ,	Тамв = +25°С		0.9	2.5	Ω	
Ron	ON-INESISIAIICE	VNOx  or  VNCx = 0.9V	TAMB = TMIN to TMAX			3	52	
INO <i>x</i> (OFF),	NOx or NCx Off-	VCOMx = 0.3  or  1.5V, VNOx	Тамв = +25°С	-1		1	nA	
INC <i>x</i> (OFF)	Leakage Current	or $VNCx = 1.5$ or $0.3V$	TAMB = TMIN to TMAX	-5		5		
ICOM <i>x</i> (OFF)	COMx Off-Leakage	VCOMx = 0.3  or  1.5V, VNOx	Тамв = +25°С	-1		1	nA	
	Current	or $VNCx = 1.5$ or $0.3V$	TAMB = TMIN to TMAX	-5		5		
ICOM <i>x</i> (ON)	COM <i>x</i> On-Leakage	VCOM <i>x</i> = 0.3 or 1.5V,	Тамв = +25°С	-2		2	54	
· · · · ·	Current	VNOx or $VNCx = 0.3$ or $1.5V$	TAMB = TMIN to TMAX	-10		10	nA	
Switch Dyna	mic Characteristics							
	Turn On Time <sup>3</sup>	VNOx or VNCx = 1.5V, RLOAD = $50\Omega$ , CLOAD = $35pF$ , Figures 12, 13	Тамв = +25°С		21	30	ns	
ton			TAMB = TMIN tO TMAX			35		
	Turn Off Time <sup>3</sup>	$V_{NOx}$ or $V_{NCx} = 1.5V$ ,	Тамв = +25°С		12	20		
tOFF		$RLOAD = 50\Omega$ , CLOAD = 35pF, Figures 12, 13	TAMB = TMIN to TMAX			25	ns	
	VNOx or V	VNOx or VNCx = $1.5V$ ,	Тамв = +25°С		8			
<b>t</b> BBM	Break-Before-Make <sup>3</sup>	RLOAD = 50Ω, CLOAD = 35p, Figure 14, (AS1743)	TAMB = TMIN to TMAX	1			ns	
Q	Charge Injection	Vgen = 1.8V, Rgen = 0,	8-pin MSOP		6		Эq	
Q	Charge Injection	CLOAD = 1.0nF, Figure 15	8-pin SOT23		2.5		ρC	
Viso	Off-Isolation <sup>4</sup>	f = 1MHz, VCOM $x = 1VRMS$ , RLOAD = 50Ω, CLOAD = 5pF, Figure 17			-50		dB	
	Crosstalk <sup>5</sup>	f = 1MHz, VCOMx = 1VRMS, RLOAD = 50Ω, CLOAD = 5pF, Figure 17			-100		dB	
Logic Input						· I	-	
Vін	Input Logic High			1			V	
VIL	Input Logic Low					0.4	V	
lin	Input Leakage Current	$V_{INx} = 0 \text{ or } V +$		-1000	0.1	1000	nA	

1.  $\Delta RON = RON(MAX) - RON(MIN)$ .

2. Flatness is defined as the difference between the maximum and the minimum value of ON-resistance as measured over the specified analog signal ranges.

3. Guaranteed by design.

4. Off-Isolation = 20log10(VCOMx/VNOx), VCOMx = output, VNOx = input to off switch.

5. Between two switches.

## **6** Typical Operating Characteristics

Figure 2. Charge Injection vs. Output Voltage; SOT23

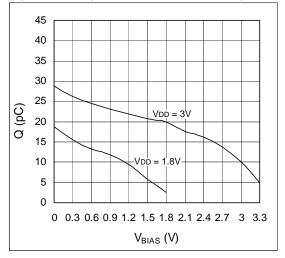
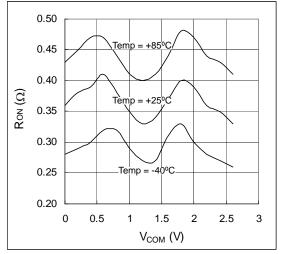


Figure 4. RON vs. VCOM and Temperature; VDD = 2.7V





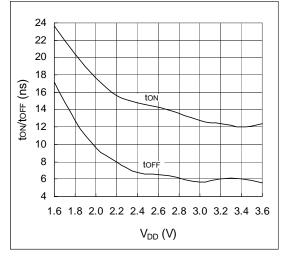


Figure 3. Charge Injection vs. Output Voltage; MSOP

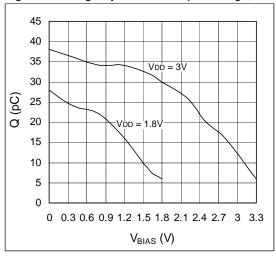


Figure 5. RON vs. VCOM

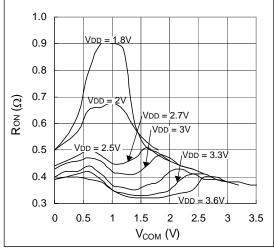
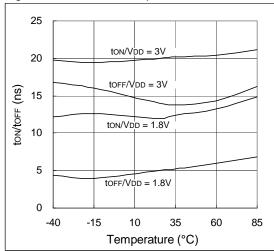


Figure 7. ton/toff vs. Temperature



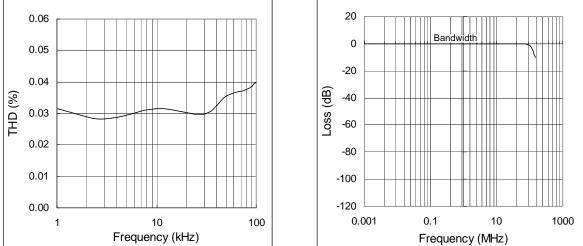


Figure 8. THD vs. Frequency;  $R_{LOAD} = 32\Omega$ ,  $V_{DD} = 3V$ 

Figure 9. Frequency Response

## 7 Pinout

### **Pin Assignments**

Figure 10. MSOP Pin Assignments (Top View)

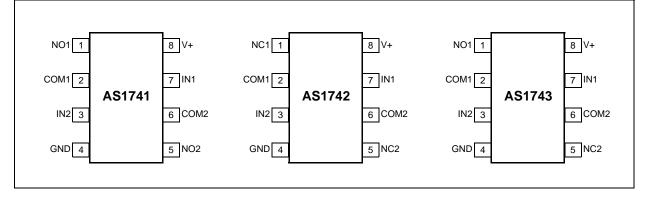
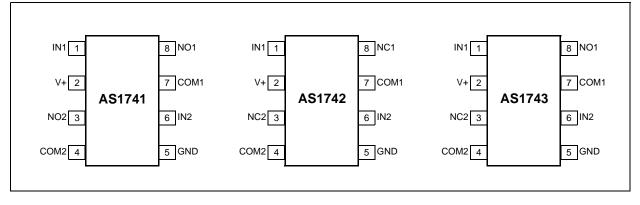


Figure 11. SOT23 Pin Assignments (Top View)



### **Pin Descriptions**

Table 6. Pin Descriptions

Pin Number	Pin Name	Description
	COM1	Analog Switch 1 Common
	COM2	Analog Switch 2 Common
	GND	Ground
	IN1	Analog Switch 1 Logic Control Input
See Figure 10	IN2	Analog Switch 2 Logic Control Input
and Figure 11	NC1	Analog Switch 1 Normally Closed Terminal
	NC2	Analog Switch 2 Normally Closed Terminal
	NO1	Analog Switch 1 Normally Open Terminal
	NO2	Analog Switch 2 Normally Open Terminal
	V+	Input Supply Voltage. +1.6 to +3.6V

## 8 Detailed Description

The AS1741/AS1742/AS1743 are low ON-resistance, low-voltage, dual analog SPST switches that operate from a single +1.6 to +3.6V supply.

CMOS process technology allows switching of analog signals that are within the supply voltage range (GND to V+).

#### **ON Resistance**

When powered from a +3V supply, the AS1741/AS1742/AS1743 low (0.8 $\Omega$ , max) ON-resistance allows high-speed, continuous signals to be switched in a variety of applications. All devices have very low Ron flatness (0.18 $\Omega$ , max) so they can meet or exceed the low-distortion audio requirements of modern portable audio devices.

#### **Bi-Directional Switching**

Pins NOx, NCx, and COMx are bi-directional and can be used as inputs or outputs.

### **Analog Signal Levels**

Analog signals ranging over the entire supply voltage range (V+ to GND) can be passed with very little change in ON-resistance (see Typical Operating Characteristics on page 5).

### **Logic Inputs**

The AS1741/AS1742/AS1743 logic inputs can be driven up to +3.6V regardless of the supply voltage value. For example, with a +1.8V supply, INx may be driven low to GND and high to +3.6V. This allows the devices to interface with +3V systems using a supply of less than 3V.

## **9** Application Information

### **Power Supply Sequencing**

Proper power-supply sequencing is critical for proper switch operation. The power supplies should be started up in the following sequence:

1. V+

2. NO*x*, NC*x*, COM*x* 

Note: Operation beyond the absolute maximum ratings (see page 2) may permanently damage the devices.

### **Power Supply Bypass**

Power supply connections to the devices must maintain a low impedance to ground. This can be done using a bypass capacitor, which will also improve noise margin and prevent switching noise propagation from the V+ supply to other components.

A 0.1µF bypass capacitor, connected from V+ to GND (see Figure 17 on page 11), is adequate for most applications.

### **Logic Inputs**

Driving INx Rail-to-Rail will help minimize power consumption.

### **Layout Considerations**

High-speed switches require proper layout and design procedures for optimum performance.

- Short, wide traces should be used to reduce stray inductance and capacitance.
- Bypass capacitors should be as close to the device as possible.
- Large ground planes should be used wherever possible.

### **Timing Diagrams and Test Setups**

Figure 12. AS1741/AS1743 Test Circuit and Timing Diagram

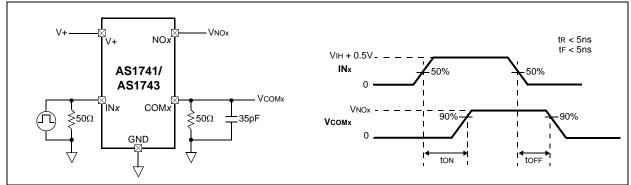
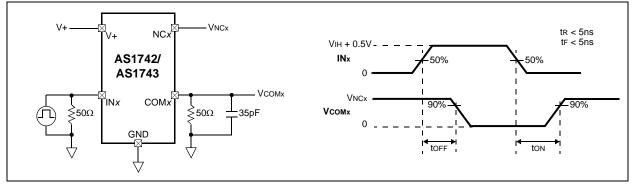
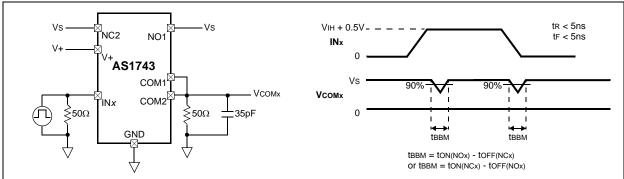


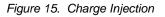
Figure 13. AS1742/AS1743 Test Circuit and Timing Diagram



Timing Diagrams and Test Setups







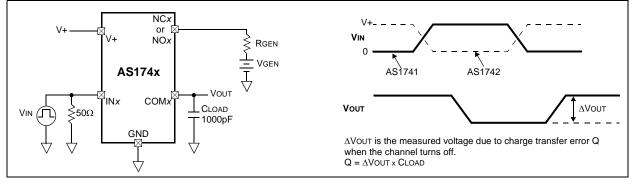
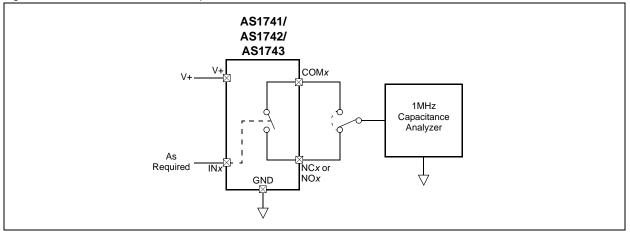
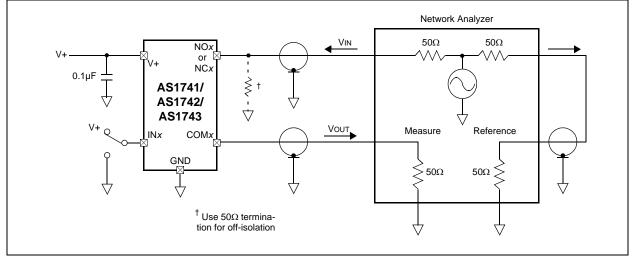


Figure 16. NOx, NCx, and COMx Capacitance



#### Timing Diagrams and Test Setups





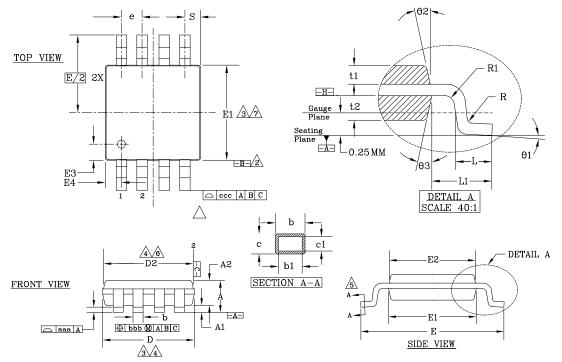
#### Notes:

- 1. Measurements are standardized against short-circuit at socket terminals.
- 2. Off-isolation is measured between COMx and the off NCx/NOx terminal of each switch. Off-isolation = 20log(Vout/VIN).
- 3. Signal direction through the switch is reversed; worst values are recorded.

## **10 Package Drawings and Markings**

The devices are available in an 8-pin MSOP package and an 8-pin SOT23 package.

#### Figure 18. 8-pin MSOP Package

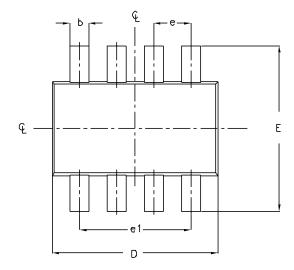


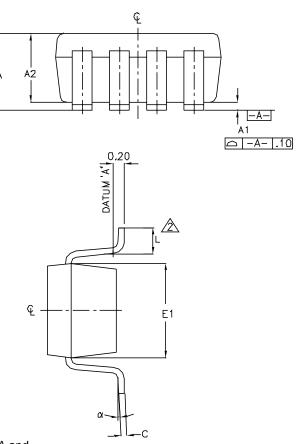
#### Notes:

- 1. All dimensions are in millimeters, angles in degrees, unless otherwise specified.
- 2. Datums B and C to be determined at datum plane H.
- 3. Dimensions D and E1 are to be determined at datum plane H.
- 4. Dimensions D2 and E2 are for top package; dimensions D and E1 are for bottom package.
- 5. Cross section A-A to be determined at 0.13 to 0.25mm from lead tip.
- 6. Dimensions D and D2 do not include mold flash, protrusion, or gate burrs.
- 7. Dimensions E1 and E2 do not include interlead flash or protrusion.

Symbol	Тур	±Tol	Symbol	Тур	±Tol
A	1.10	Max	b	0.33	+0.07/-0.08
A1	0.10	±0.05	b1	0.30	±0.05
A2	0.86	±0.08	С	0.18	±0.05
D	3.00	±0.10	c1	0.15	+0.03/-0.02
D2	2.95	±0.10	θ1	3.0°	±3.0°
E	4.90	±0.15	θ2	12.0°	±3°
E1	3.00	±0.10	θ <b>3</b>	12.0°	±3°
E2	2.95	±0.10	L	0.55	±0.15
E3	0.51	±0.13	L1	0.95BSC	-
E4	0.51	±0.13	aaa	0.10	-
R	0.15	+0.15/-0.08	bbb	0.08	-
R1	0.15	+0.15/-0.08	CCC	0.25	-
t1	0.31	±0.08	е	0.65 BSC	-
t2	0.41	±0.08	S	0.525 BSC	-

Figure 19. 8-pin SOT23 Package





#### Notes:

- 1. All dimensions are in millimeters.
- 2. Foot length measured at intercept point between datum A and lead surface.
- 3. Package outline exclusive of mold flash and metal burr.
- 4. Package outline inclusive of solder plating.
- 5. Complies with EIAJ SC74 (6-lead version).
- 6. PKGST0005 (Rev B) refer to SOT23 8-lead SOT23-D-2019 (Rev C) package outline.

Symbol	Min	Max		
A	0.90	1.45		
A1	0.00	0.15		
A2	0.90	1.30		
b	0.22	0.38		
С	0.09	0.20		
D	2.80	3.10		
E	2.60	3.00		
E1	1.50	1.75		
L	0.35	0.55		
е	0.65REF			
e1	1.95REf			
α	0°	10º		

## **11 Ordering Information**

The devices are available as the standard products shown in Table 7.

#### Table 7. Ordering Information

Model	Markings	Description	Delivery Form	Package
AS1741G		Dual SPST Switch	Tube	8-pin MSOP
AS1741G-T		Dual SPST Switch	Tape and Reel	8-pin MSOP
AS1741H-T <sup>†</sup>	ASJL	Dual SPST Switch	Tape and Reel	8-pin SOT23
AS1742G		Dual SPST Switch	Tube	8-pin MSOP
AS1742G-T		Dual SPST Switch	Tape and Reel	8-pin MSOP
AS1742H-T	ASJK	Dual SPST Switch	Tape and Reel	8-pin SOT23
AS1743G		Dual SPST Switch	Tube	8-pin MSOP
AS1743G-T		Dual SPST Switch	Tape and Reel	8-pin MSOP
AS1743H-T <sup>†</sup>	ASJM	Dual SPST Switch	Tape and Reel	8-pin SOT23

<sup>†</sup> Available upon request

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